



ADVANCED
INTERCONNECTIONS.

Where Research Becomes Reality . . . Worldwide

PRODUCT BULLETIN 2009-01

PRODUCT:
Flip-Top™ BGA Socket

DATE:
July 1, 2009

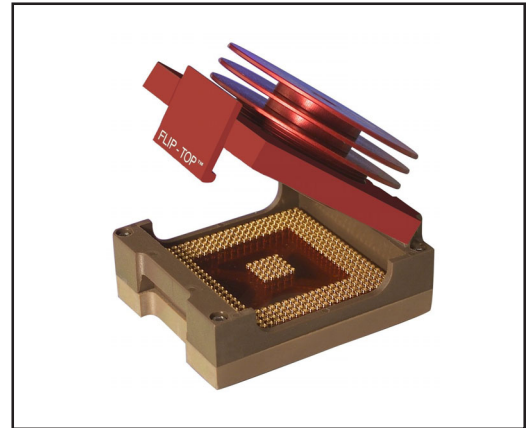
PART NUMBER SERIES:
FRG, FRH

TYPE:
Product Enhancement

To meet the ever increasing demands for higher pin count BGA packages, Advanced's Flip-Top™ BGA Sockets in both through-hole versions at 1.00mm and 1.27mm pitch and surface mount versions at 1.27mm pitch have been redesigned to improve durability and product performance. The changes will be implemented on all open and new orders as of June 22, 2009.

Product improvements include:

- Replacement of the molded plastic lid and latch with aluminum components and a higher-force tension spring
- Increased the size of the hex feature on the heat sink and coin screw clamps from 1/8" to 6mm, allowing use of a larger allen wrench to facilitate more robust handling during clamp engagement



This enhanced design is more robust, for better performance when turning the heat sink or coin screw to engage the BGA or LGA device and provides improved performance over multiple cycles.

The enhancements described above have no effect on the overall size (X, Y, or Z dimensions) of the Flip-Top™ BGA Socket and require no part number changes. Customers will be able to differentiate between old and new styles by the revision number on the product drawing. The only visible difference is the new anodized aluminum lid and latch.

Please contact customer service with any questions.

Advanced Interconnections Corp. ■ 5 Energy Way ■ P.O. Box 1019 ■ West Warwick, Rhode Island U.S.A.
Tel: (800) 424-9850 ■ (401) 823-5200 ■ FAX: (401) 823-8723
E-mail: info@advanced.com ■ Web Site: <http://www.advanced.com>